











TPS92200

SLVSER4-MAY 2020

TPS92200 4-V to 30-V Input Voltage, 1.5-A Output Current, Synchronous Buck LED Driver With Flexible Dimming Options

Features

- 4-V to 30-V Wide input range
- Integrated 150-m Ω and 90-m Ω MOSFETs for 1.5-A, continuous output current
- Ultra-low shut-down current: 1-μA
- Ultra-low output discharge current from load: 1-µA
- 1-MHz Switching frequency
- Maximum duty cycle up to 99%
- Peak current mode with internal compensation
- Flexible dimming options:
 - TPS92200D1: PWM dimming with digital input and analog dimming with analog input
 - TPS92200D2: Analog dimming with digital
- Ultra-low and accurate FB voltage: 99 mV ±3 mV
- Full protection features:
 - LED open-load protection
 - LED+ short-to-GND protection with auto-retry
 - LED+ and LED- short circuitry protection with auto-retry
 - Sense-resistor open-load and short-to-GND protection with auto-retry
 - Thermal shutdown protection with auto-retry
- SOT23(6) Package

2 Applications

- Video surveillance IR/White LED driver
- Facial recognition IR LED driver
- Stage lighting LED driver
- General industrial and commercial illumination
- Medical UV LED driver
- AA or Li-Ion battery charger

3 Description

The TPS92200 device is a 1.5-A synchronous buck LED driver with 30-V maximum input voltage. By integrating the high-side and low-side NMOS switches, the TPS92200 device provides high power density with high efficiency in an ultra-small solution size. The TPS92200 device uses peak-current-mode control and full internal compensation to provide high transient response performance over a wide range of operating conditions.

The TPS92200 device supports flexible dimming methods. TPS92200D1 implements both PWM and analog dimming modes. In PWM dimming mode, LEDs will be turned on and off according to PWM duty cycle periodically. Its analog dimming mode is achieved by changing the internal reference voltage proportional to the voltage level of the analog input in 5% to 100% range. TPS92200D2 implements deeper analog dimming by changing the internal reference voltage proportional to the duty cycle of the PWM signal input in 1% to 100% range.

For safety and protection the TPS92200 devices implement full protections include LED open, LED+ short to GND, LED short, sense resistor open and short, and device thermal protection.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPS92200D1DDCR	SOT-23-THIN (6)	1.60 mm x 2.90 mm
TPS92200D2DDCR	SOT-23-THIN (6)	1.60 mm x 2.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic

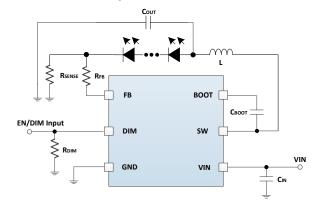








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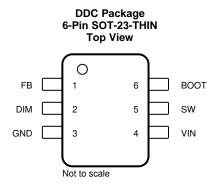
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4 Revision History

DATE	REVISION	NOTES
May 2020	*	Advance Information release



5 Pin Configuration and Functions



Pin Functions

	PIN	TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.	I I PE	DESCRIPTION
BOOT	6	0	A bootstrap capacitor is required between BOOT and SW
FB	1	I	LED current detection feedback
GND	3	G	Power ground
DIM	2	I	Dimming input. In PWM dimming mode, LED current is turned ON and OFF according to PWM duty cycle periodically (TPS92200D1). In analog dimming mode, the internal reference is proportional to the analog voltage on DIM pin (TPS92200D1) or the PWM duty input (TPS92200D2).
SW	5	0	Switching node to external inductor
IN	4	Р	Input supply voltage

⁽¹⁾ I = Input, O = Output, P = Supply, G = Ground

TEXAS INSTRUMENTS

6 Specifications

6.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
	IN	-0.3	32	V
Input voltage range, V _I	DIM	-0.3	7	V
	FB	-0.3	7	V
	BOOT-SW	-0.3	7	V
Output voltage range, VO	SW	-0.3	32	V
	SW (20 ns transient)	-5	32	V
Operating junction temperature, T _J		-40	150	°C
Storage temperature range, T _{stg}		–65	150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
\/	Electrostatic	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	\/
V _(ESD)	discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±500	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

	,	MIN	MAX	UNIT
		IVIIIN	IVIAA	UNIT
	IN	4	30	V
Input voltage range	DIM	-0.1	6	V
	FB	-0.1	6	V
Output valtage range	BOOT-SW	-0.1	6	V
Output voltage range	SW	-0.1	30	V
Operating junction temperature, T _J		-40	125	°C

6.4 Thermal Information

		TPS92200	
	THERMAL METRIC ⁽¹⁾	DDC (SOT23-6)	UNIT
		6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	123.4	°C/W
R ₀ JC(top)	Junction-to-case (top) thermal resistance	60.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	41.4	°C/W
ΨЈТ	Junction-to-top characterization parameter	12.3	°C/W
ΨЈВ	Junction-to-board characterization parameter	40.9	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.5 Electrical Characteristics

The electrical ratings specified in this section apply to all specifications in this document, unless otherwise noted. These specifications are interpreted as conditions that do not degrade the device parametric or functional specifications for the life of the product containing it. $T_J = -40$ °C to +125°C, $V_{IN} = 4$ V to 30 V, (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT SUPPLY	(
V _{IN}	Input voltage range		4		30	V
	Vdom.olfo.no.lo.ol.out	Rising V _{IN}	3.5	3.7	3.9	V
V _{IN_UVLO}	V _{IN} undervoltage lockout	Falling V _{IN}	3.3	3.5	3.7	V
	Hysteresis			0.2		V
I _{SD}	Shut down current from V _{IN}	V _{IN} = 12 V, V _{DIM} = 0 V		1	3	μΑ
I _{DISC}	Discharge current from SW and BOOT	V_{IN} floating, $V_{DIM} = 0$ V, $V_{SW} = 12$ V		1	3	uA
I _{OP}	Normal operating current	V_{DIM} = 3.3 V, FB voltage >1V, no switching		0.5	1	mA
V_{DIM_L}	Low-level input voltage				0.3	V
V_{DIM_H}	High-level input voltage		0.65			V
V _{ANA}	Analog dimming range (TPS92200D1 only)	V _{DIM} = 3.3 V	0.65		1.2	٧
t _{DIM_ON1}	DIM minimum on time to enable device (TPS92200D2 only)	V _{DIM} = 3.3 V		190	300	nS
t _{DIM_ON2}	DIM minimum on time when PWM dimming (TPS92200D2 only)	V _{DIM} = 3.3 V			150	nS
t _{DIM_OFF}	DIM minimum off time to disable device	V _{DIM} = 0 V		36		mS
FEEDBACK AN	ND ERROR AMPLIFIER					
V_{FB_REF}	FB pin reference voltage	V _{DIM} = 3.3 V	96	99	102	mV
V_{FB_OVP}	FB pin over voltage protection threshold	V _{DIM} = 3.3 V		140		mV
V_{FB_DMAX}	FB reference voltage when maximum dimming input (TPS92200D1 only)	V _{DIM} = 1.2 V		99		mV
V	FB reference voltage when minimum dimming input (TPS92200D1 only)	V _{DIM} = 0.65 V		5		mV
V _{FB_DMIN}	FB reference voltage when minimum dimming duty cycle (TPS92200D2 only)	DIM pin duty cycle <= 3%		1		mV
POWER STAGE	E					
R _{HS}	High-side FET on resistance	V _{IN} ≥ 5 V		150		$m\Omega$
R_LS	Low-side FET on resistance	V _{IN} ≥ 5 V		90		$m\Omega$
CURRENT LIMI	CURRENT LIMIT					
I _{LIM_HS}	High-side current limit		2.9	3.3	4	Α
I _{LIM_LS_SOUR}	Low-side sourcing current limit		2.4	3	3.6	Α
I _{LIM_LS_SINK}	Low-side sinking current limit		1.4	1.8	2.4	Α
THERMAL PRO	DTECTION					
T	Thermal shutdown temperature			165		°C
T _{TSD}	Hysteresis			15		°C





6.6 Timing Requirements

		MIN	TYP	MAX	UNIT
Auto-Retry Timi	ing	·			
t _{RETRY_ON}	Auto-retry on-time		512		Cycles
t _{RETRY_OFF}	Auto-retry off-time		60		ms
SOFT START					
t _{SS}	Internal soft-start time		0.5		ms

6.7 Switching Characteristics

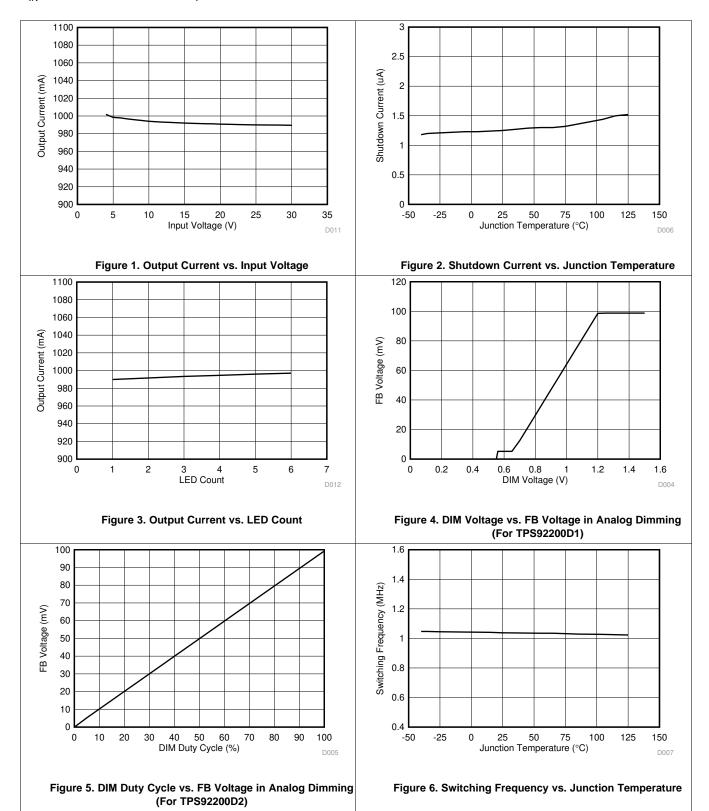
 $T_J = -40$ °C to +125 °C, $V_{IN} = 4V$ to 30 V, (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{sw}	Switching frequency		0.8	1	1.2	MHz
D _{MAX}	Maximum duty cycle			99%		
t _{MIN_ON}	Minimum on time			75	100	ns
t _{MIN_OFF}	Minimum off time			65	90	ns
t _{MAX_ON}	Maximum on time			6.6		us



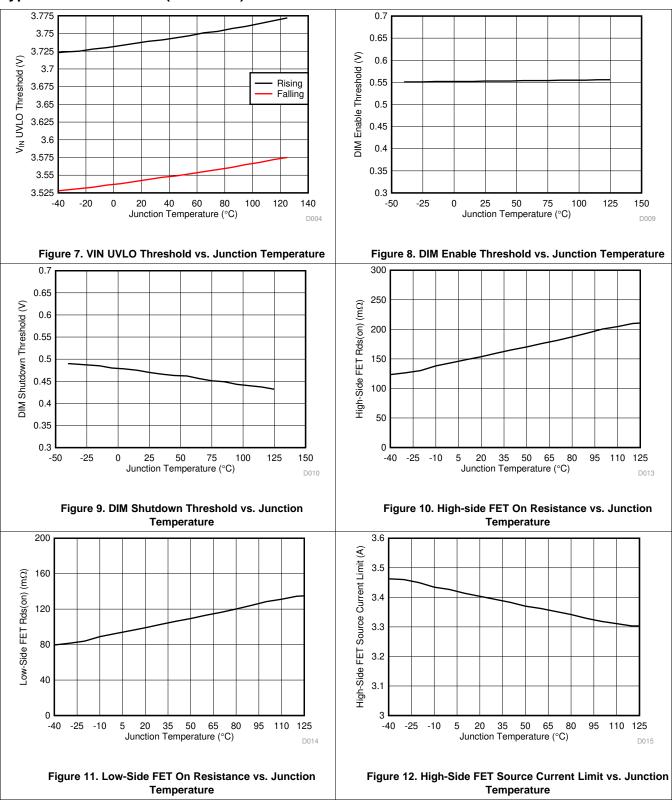
6.8 Typical Characteristics

V_{IN} = 12V, unless otherwise specified



TEXAS INSTRUMENTS

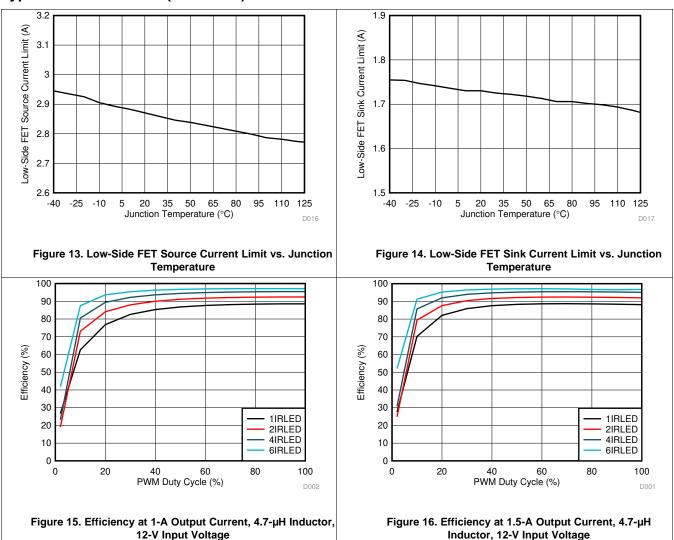
Typical Characteristics (continued)



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Typical Characteristics (continued)





7 Detailed Description

7.1 Overview

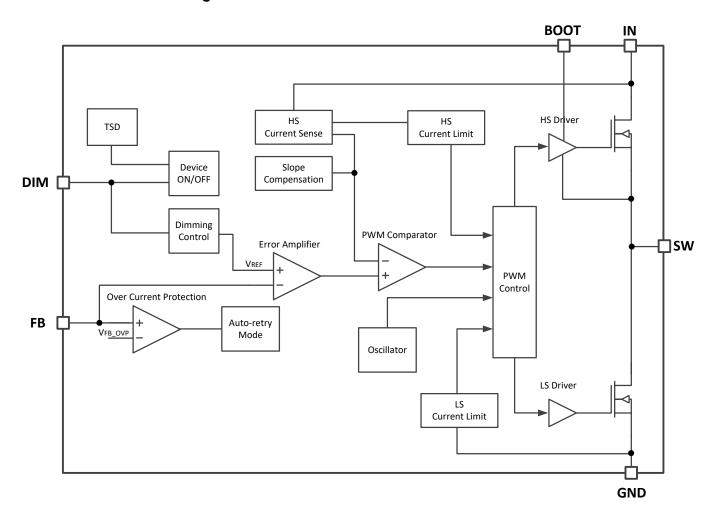
The TPS92200 device is a 1.5-A synchronous buck LED driver with 30-V maximum input voltage. By integrating the high-side and low-side NMOS switches, the TPS92200 device provides high power density with high efficiency in an ultrasmall solution size.

The TPS92200 device is fully internally compensated without additional external components, which enables a simple design on a limited board space. The device uses peak current mode control to regulate the LED current with high accuracy. Switching frequency is internally set to 1 MHz, allowing the use of extremely small surfacemount inductors and chip capacitors.

The TPS92200 devices support flexible dimming methods. TPS92200D1 implement both PWM and analog dimming modes. In PWM dimming mode, LED will be turn on and off according to PWM duty cycle periodically. Its analog dimming mode is achieved by changing the internal reference voltage proportional to the voltage level of the analog input in 5% to 100% range. TPS92200D2 implement deeper analog dimming by changing the internal reference voltage proportional to the duty cycle of the PWM signal input in 1% to 100% range.

For safety and protection the TPS92200 devices implement full protections include LED open, LED+ short to GND, LED short, sense resistor open and short, and device thermal protection. Hiccup mode is triggered at current limit or FB pin over-voltage scenario to avoid the device overheats.

7.2 Functional Block Diagram





7.3 Feature Description

7.3.1 Peak-Current-Mode PWM Control

The TPS92200 device uses peak-current-mode control and full internal compensation to provide high transient response performance over a wide range of operating conditions. The switching frequency is internally set to 1 MHz when the minimum off time $t_{MIN\ OFF}$ is not triggered, thus minimize the external inductor and capacitor size.

During each switching cycle, when the high-side power switch is turned on, the load current is sensed through the external sense resistor, R_{SENSE} . The sensed voltage on the FB pin is compared with the internal voltage reference, V_{REF} , through the error amplifier. The output of the error amplifier, V_{COMP} , is compared with the real-time current, $I_{\text{HS_SENSE}}$, going through the high-side power switch. Slope compensation circuitry is implemented in the device to prevent sub-harmonic oscillations as the duty cycle increases in peak-current-control mode. When the peak value of $V_{\text{HS_SENSE}}$ reaches V_{COMP} in the PWM comparator, the high-side power switch is turned off and the low-side NMOS is turned on at the same time. The low-side power switch stays turned on until the end of the PWM cycle. Thus, by regulating the real-time peak current in each switching cycle, the device controls the load current at the target value.

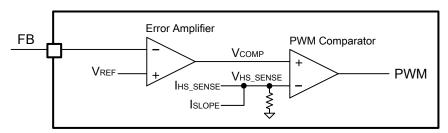


Figure 17. Error Amplifier and PWM Comparator

7.3.2 Setting LED Current

The LED current is set by the external resistor between the LEDs cathode and GND, since the FB pin voltage reference $V_{FB\ REF}$ is fixed at 99 mV, the sensing resistor can be calculated using Equation 1.

$$R_{SENSE} = \frac{V_{FB_REF}}{I_{LED}}$$
 (1)

7.3.3 Internal Soft Start

The TPS92200 device implements the internal soft-start function. The V_{REF} ramps smoothly during the soft-start period. The internal soft-start period is set as t_{SS} , 0.5 ms typically.

7.3.4 Input Undervoltage Lockout

The device implements internal undervoltage-lockout (UVLO) circuitry on the IN pin. The device is disabled when the IN pin voltage falls below the internal IN UVLO threshold, 3.5 V typical. The internal IN UVLO threshold has a hysteresis of 0.2 V typical.

7.3.5 Bootstrap regulator

The TPS92200 integrates a bootstrap regulator inside, and requires an external capacitor between the BOOT and SW pins to provide the gate driver voltage for the high-side power switch. A 0.1-µF ceramic capacitor with an X7R or X5R dielectric is recommended because of the stable characteristics over temperature and voltage.

7.3.6 Maximum Duty Cycle

For a buck LED driver, the maximum duty cycle is limited by the minimum off time t_{MIN_OFF} and switching frequency. To achieve the maximum brightness when the input voltage is close to output voltage, the TPS92200 device has a mechanism to decrease the switching frequency. This mechanism extends the on-time up to t_{MAX_ON} , 6.6 μ s (typical). With this function, the TPS92200 device maximum duty cycle is able to go up to t_{MAX} , 99% (typical).



Feature Description (continued)

7.3.7 Over-current Protection

The device is protected from overcurrent conditions by cycle-by-cycle current limiting on both the high-side NMOS and the low-side NMOS.

7.3.7.1 High-Side MOSFET Overcurrent Protection

During each switching on cycle, the high-side sense voltage, V_{HS_SENSE} , is compared with V_{COMP} to generate the PWM duty cycle. In order to prevent an overcurrent stress, V_{COMP} is internally clamped to set the high-side NMOS current limit as I_{LIM_HS} . When the peak of I_{HS_SENSE} exceeds I_{LIM_HS} , the high-side MOSFET is turned off and the low-side MOSFET is turned on accordingly. An auto-retry mechanism is implemented for this case, if an output over-current condition occurs for more than auto-retry on time t_{RETRY_ON} , which is programmed for 512 switching cycles, the device shuts down for an auto-retry off-time t_{RETRY_OFF} , which is 60ms typicially.

7.3.7.2 Low-Side MOSFET Sourcing Overcurrent Protection

During each switching off-cycle, the low-side MOSFET is turned on and the conduction current is monitored by the internal circuitry. At the end of every clock cycle, the low-side MOSFET sourcing current is compared to the internally set low-side sourcing-current limit, $I_{LIM_LS_SOUR}$. If the low-side sourcing-current limit is exceeded, the high-side MOSFET does not turn on and the low-side MOSFET stays on for the next clock cycle. The high-side MOSFET turns on again when the low-side current is below the low-side sourcing current limit at the start of a cycle.

7.3.7.3 Low-Side MOSFET Sinking Overcurrent Protection

During each switching off-cycle, the device also monitors the sinking current of the low-side MOSFET by detecting the voltage across it and sets an sinking overcurrent limit, I_{LIM_LS_SINK}, to protect the low-side power switch from overstress. When the peak of the sinking current reaches I_{LIM_LS_SINK}, both the high-side MOSFET and low-side MOSFET are turned off. The high-side MOSFET turns on again when the low-side current is below the low side sinking current-limit at the start of a new cycle.

Feature Description (continued)

7.3.8 Fault Protection

The device is protected from several kinds of fault conditions, such as LED open and short, sense resistor open and short, and thermal shutdown.

Table 1. Protections

TYPE	CRITERION	BEHAVIOR
LED open load	V _{FB} close to 0 mV	The device keeps maximum duty cycle turn-on
LED+ and LED- short circuit-	V _{FB} > V _{FB_OVP}	When $V_{FB} > V_{FB_OVP}$, the device keeps the minimum on-time, and starts the auto-retry timer. During the auto-retry mode, the device is protected by the overcurrent limits.
LED+ short to GND	High-side or low-side NMOS current limit triggered	When the high-side or low-side MOSFET current limit is triggered, the device starts the auto-retry timer.
Sense-resistor open load	V _{FB} > V _{FB_OVP}	When $V_{\text{FB}} > V_{\text{FB}_\text{OVP}}$, the device keeps the minimum on-time, and starts the auto-retry timer.
Sense-resistor short circuit to GND	High-side or low-side MOSFET current limit triggered	When the high-side or low-side MOSFET current limit is triggered, the device starts the auto-retry timer.
Thermal shutdown	T _J > T _{TSD}	Disable the device when $T_J > T_{TSD}$, re-activate the device when T_J falls below the hysteresis level.

7.3.8.1 LED Open-Load Protection

When LED load is open, V_{FB} voltage will be low. The internal error amplifier output voltage, V_{COMP} is driven high and clamped. The high-side MOSFET is forced to turn on with the maximum PWM duty cycle, D_{MAX} .

7.3.8.2 LED+ and LED- Short Circuit Protection

When LED+ and LED- are shorted, V_{FB} is higher than internal reference voltage V_{REF} , and internal error amplifier output voltage V_{COMP} is driven low and clamped. The high-side MOSFET is forced to turn on with the minimum on-time each cycle, t_{MIN_ON} . In this case, if the output voltage is too low, the inductor current may not be able to balance in a cycle, causing current runaway. Finally, the inductor current is clamped by low side MOSFET sourcing current limit $I_{LIM_LS_SOUR}$ which is 3A typical. If V_{FB} rises higher than V_{FB_OVP} , the device starts the autoretry timer. Once the counter t_{RETRY_ON} expires, the device shuts down and starts another counter t_{RETRY_OFF} . During the shutdown period, both high-side and low-side MOSFETs are turned off. Once the hiccup timer expires, TPS92200 restarts again. The device repeats these behavior until the failure condition is removed. During the auto-retry mode, the device is also protected by the overcurrent limits of both high-side power switch and low-side power switch.

7.3.8.3 LED+ Short Circuit to GND Protection

When LED+ is shorted to GND, V_{FB} is low and V_{COMP} is driven high and clamped. The high-side MOSFET is forced to turn on with maximum PWM duty cycle, once either the high-side or low-side overcurrent limit is triggered, the device starts the auto-retry counter. When the counter t_{RETRY_ON} expires, the device shuts down and starts another counter t_{RETRY_OFF} . During the shutdown period, both high-side and low-side NMOSs are switched off. The device repeats these actions until the failure condition is removed.

7.3.8.4 Sense-Resistor Open-Load Protection

When the R_{SENSE} load is open, V_{FB} is higher than V_{REF} , and V_{COMP} is driven low and clamped. The high-side NMOS is forced to turn on with the minimum on-time each cycle, t_{MIN_ON} . If V_{FB} rises higher than V_{FB_OVP} , the device starts the auto-retry timer. Once the counter t_{RETRY_ON} expires, the device shuts down and starts another counter t_{RETRY_OFF} . During the shutdown period, both high-side and low-side NMOSs are switched off. The device repeats these actions until the failure condition is removed. To prevent the FB pin from overvoltage damage during the t_{RETRY_ON} period, the FB pin implements a comparator with a 1-V threshold. If $V_{FB} > 1$ V, both high-side and low-side NMOSs are switched off immediately and the t_{RETRY_OFF} counter starts.



7.3.8.5 Sense Resistor Short Circuit-to-GND Protection

When R_{SENSE} is shorted to GND, V_{FB} is low and V_{COMP} is driven high and clamped. Once the current reaches either the high-side overcurrent limit or low-side overcurrent limit, the device starts the auto-retry counter. Once the t_{RETRY_ON} counter expires, the device shuts down and starts another counter, t_{RETRY_OFF} . During the shutdown period, both high-side and low-side NMOSs are switched off. The device repeats these actions until the failure condition is removed.

7.3.8.6 Over Voltage Protection

When the FB pin, for some reason, has a voltage higher than 1V applied, the device shuts down immediately. Both high side and low side MOSFETs are kept off, the device starts the auto-retry counter t_{RETRY_OFF}, when the counter t_{RETRY_OFF} expires, the device restarts again. If the failure still exist, TPS92200 repeats above hiccup shutdown and restart process.

7.3.8.7 Thermal Shutdown

The TPS92200 device implements a thermal shutdown mechanism to protect the device from damage due to overheating. When the junction temperature rises to 160°C (typical), the device shuts down immediately. The TPS92200 device releases thermal shutdown when the junction temperature of the device is reduced to 145°C (typical).



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7.4 Device Functional Modes

Table 2. Functional Modes

Device Name	DIM Pin Constant High	DIM Pin Constant Low	Dimming Input Type	Dimming Output Type
TPS92200D1	92200D1 Device full on Device turned off	Digital signal • Amplitude: V _H > 1.4 V and V _L < 0.3 V • Frequency: 100 Hz-2 kHz	PWM Dimming	
			Analog voltage • Amplitude: 0.65 V–1.2 V	5%-100% Analog Dimming
			Digital signal • Frequency: 20 kHz-200 kHz	1%-100% Analog Dimming

7.4.1 Enable and Disable the Device

The DIM pin performs not only the dimming function, but also the enable-and-disable function. When the V_{IN} voltage is above the UVLO threshold, the TPS92200 device can be enabled by driving the DIM pin higher than the threshold voltage V_{DIM H} for a period longer than t_{DIM ON1}. To disable the device, the DIM pin must be kept lower than the threshold voltage V_{DIM_L} for a period longer than t_{DIM_OFF}. External pulldown is required to set the device as default-disabled, because the DIM pin is designed as a high-impedance input.

7.4.2 TPS92200D1 PWM Dimming

For the TPS92200D1 version, when applying a digital signal on the DIM pin, the device enters into PWM dimming mode. The amplitude of the digital signal must be higher than 1.4 V for high level and less than 0.3 V for low level, which is out of the analog dimming range (0.65 V-1.2 V). The frequency of the digital signal is recommended to be from 100 Hz to 2 kHz to achieve good dimming accuracy. In PWM dimming mode, the output turns on and off simultaneously with the digital-input high and low pulses, respectively.

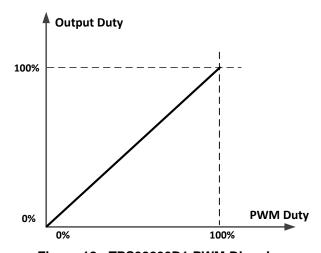


Figure 18. TPS92200D1 PWM Dimming

7.4.3 TPS92200D1 Analog Dimming

For the TPS92200D1 version, when applying an analog voltage on the DIM pin and the amplitude is between 0.65 V and 1.2 V, the device enters into analog dimming mode, and the reference voltage V_{REF} is changed proportionally to the analog input level. When $V_{DIM} = 0.65 \text{ V}$, the reference voltage is 5 mV. When $V_{DIM} = 1.2 \text{ V}$, the reference voltage is 99 mV.

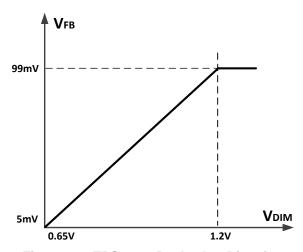


Figure 19. TPS92200D1 Analog Dimming

7.4.4 TPS92200D2 Analog Dimming

The TPS92200D2 version supports accurate analog dimming with a digital signal. When applying a digital signal on the DIM pin, the device enters into analog dimming mode, and the reference voltage V_{REF} is changed proportionally to the duty cycle of digital input.. The frequency of the digital signal must be within the range of 20 kHz to 200 kHz.

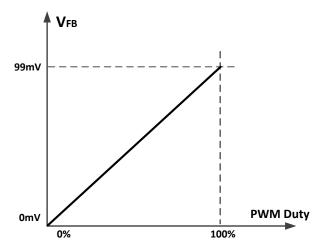


Figure 20. TPS92200D2 Analog Dimming

Product Folder Links: TPS92200

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8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPS92200 device is typically used as a buck converter to drive one or more LEDs from a 4-V to 30-V input.

8.2 Typical Application

8.2.1 TPS92200D1 12-V Input, 1.5-A, 2-Piece IR LED Driver With Analog Dimming

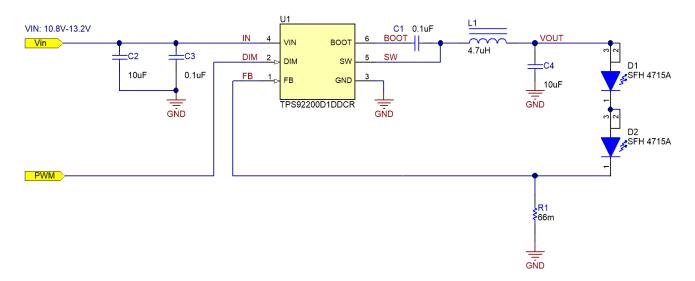


Figure 21. 12-VIN, 1.5-A, 2-piece IR LED, Analog Dimming Reference Design

8.2.1.1 Design Requirements

For this design example, use the parameters in the following table.

Table 3. Design Parameters

PARAMETER	VALUE
Input voltage range	12 V ±10%
LED forward voltage	1.75 V
Output voltage	3.6 V (1.75 × 2 + 0.1)
Maximum LED current	1.5 A
Inductor current ripple	30% of maximum LED current
LED current ripple	20mA or less
Input voltage ripple	200mV or less
Dimming type	Analog dimming with TPS92200D1: 0.65 V to 1.2 V analog input on DIM pin

STRUMENTS

8.2.1.2 Detailed Design Procedure

8.2.1.2.1 Inductor Selection

Use Equation 2 to calculate the recommended value of the output inductor L.

$$L = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times K_{IND} \times I_{LED} \times f_{SW}}$$

where

- K_{IND} is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current.
- I_{LED} is the maximum LED current.
- V_{OUT} is the sum of the voltage across the LED load and the voltage across the sense resistor.

In general, the value of K_{IND} is suggested between 0.2 and 0.4. For the application that can tolerate higher LED current ripple or use larger output capacitors, one can choose 0.4 for K_{IND}, otherwise, smaller K_{IND} like 0.2 can be chosen to get smaller LED current ripple.

With the chosen inductor value, the user can calculate the actual inductor current ripple using Equation 3.

$$I_{L(ripple)} = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times L \times f_{SW}}$$
(3)

For TPS92200, the inductor current ripple is also suggested to be larger than 300mA to guarantee loop stability. If the calculated inductor current ripple is less than 300mA. Smaller inductor is suggested.

The inductor RMS current and saturation-current ratings must be greater than those seen in the application. This ensures that the inductor does not overheat or saturate. During power up, transient conditions, or fault conditions, the inductor current can exceed its normal operating current. For this reason, the most conservative approach is to specify an inductor with a saturation current rating equal to or greater than the converter current limit. This is not always possible due to application size limitations. The peak-inductor-current and RMS current equations are shown in Equation 4 and Equation 5.

$$I_{L(peak)} = I_{LED} + \frac{I_{L(ripple)}}{2}$$

$$I_{L(rms)} = \sqrt{I_{LED}^2 + \frac{I_{L(ripple)}^2}{12}}$$
(4)

$$I_{L(rms)} = \sqrt{I_{LED}^2 + \frac{I_{L(ripple)}^2}{12}}$$
(5)

In this design, $V_{IN(max)}$ = 13.2 V, V_{OUT} = 3.6 V, I_{LED} = 1.5 A, choose K_{IND} = 0.3, the calculated inductance is 5.8- μ H. A 4.7- μ H inductor is chosen. With this inductor, the ripple, peak, and RMS currents of the inductor are 0.56 A, 1.78 A and 1.51 A respectively. The chosen inductor has ample margin.

8.2.1.2.2 Input Capacitor Selection

The device requires an input capacitor to reduce the surge current drawn from the input supply and the switching noise from the device. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. For most applications, a 10-μF capacitor with an additional 0.1-μF capacitor from VIN to GND to provide additional high-frequency filtering is enough. The input capacitor voltage rating must be greater than the maximum input voltage. Use equation x to calculate the input ripple voltage, where ESR_{CIN} is the ESR of input capacitor. Ceramic capacitance tends to decrease as the applied DC voltage increases. This depreciation must be accounted for when calculate input ripple voltage.

In this design, a 10-µF, 35-V X7R ceramic capacitor is chosen. This yields around 40-mV input ripple voltage.

8.2.1.2.3 Output Capacitor Selection

The output capacitor reduces the high-frequency ripple current through the LED string. Various guidelines disclose how much high-frequency ripple current is acceptable in the LED string. Excessive ripple current in the LED string increases the RMS current in the LED string, and therefore the LED temperature also increases.

Calculate the total dynamic resistance of the LED string (R_{LED}) using the LED manufacturer's datasheet.



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- 2. Calculate the required impedance of the output capacitor (ZOUT) given the acceptable peak-to-peak ripple current through the LED string, $I_{LED(ripple)}$. $I_{L(ripple)}$ is the peak-to-peak inductor ripple current as calculated previously in inductor selection.
- Calculate the minimum effective output capacitance required.
- 4. Increase the output capacitance appropriately due to the derating effect of applied dc voltage.

See Equation 6, Equation 7, and Equation 8.

$$R_{LED} = \frac{\Delta V_F}{\Delta I_F} \times \# \ of \ LEDs \tag{6}$$

$$Z_{COUT} = \frac{(R_{LED} + R_{SENSE}) \times I_{LED(ripple)}}{I_{L(ripple)} - I_{LED(ripple)}}$$
(7)

$$C_{OUT} = \frac{1}{2\pi \times f_{SW} \times Z_{COUT}} \tag{8}$$

Once the output capacitor is chosen, Equation 9 can be used to estimate the peak-to-peak ripple current through the LED string.

$$I_{LED(ripple)} = \frac{Z_{COUT} \times I_{L(ripple)}}{Z_{COUT} + R_{LED} + R_{SENSE}}$$
(9)

OSRAM SFH4715A IR LED is used here. The dynamic resistance of this LED is 0.29 ohm at 1.5-A forward current. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. In this design, a 10-µF, 35-V X7R ceramic capacitor is chosen, the part number is GRM32ER7YA106KA12L. The calculated ripple current of the LED is about 23.8mA.

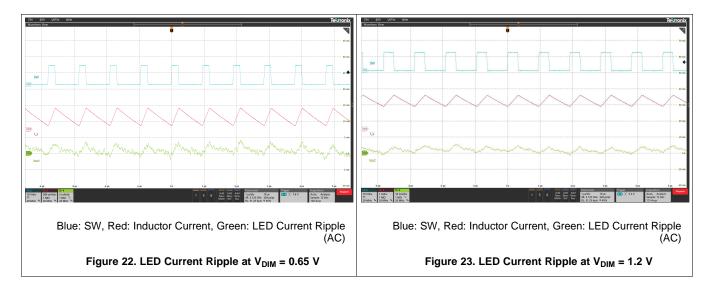
8.2.1.2.3.1 Sense Resistor Selection

The maximum LED current is 1.5 A at 100% PWM duty and the corresponding V_{REF} is 99 mV. By using Equation 1, calculate the needed sense resistance at 66 m Ω . Pay close attention to the power consumption of the sense resistor in this design at 148.5 mW, and make sure the chosen resistor has enough margin in its power rating.

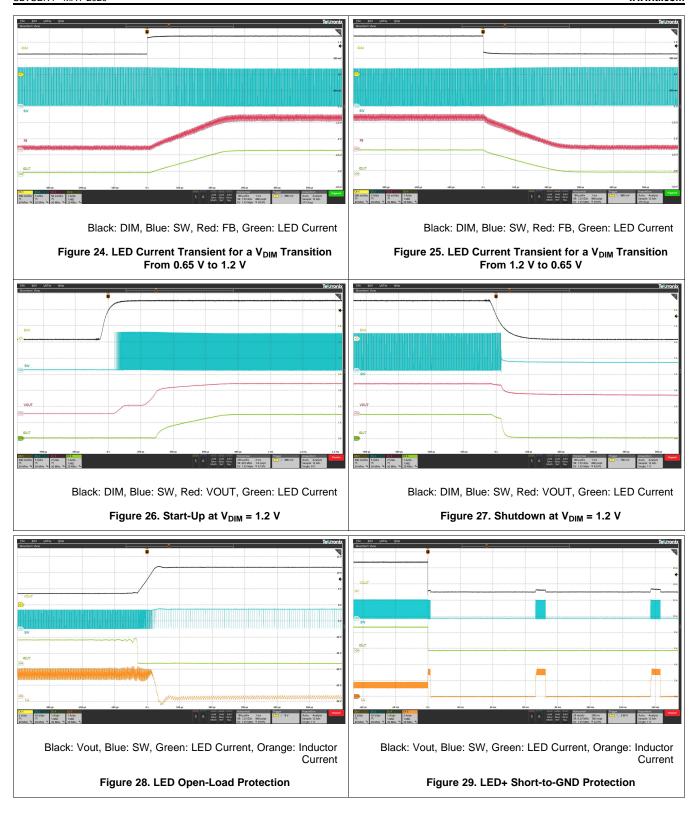
8.2.1.2.3.1.1 Other External Components Selection

In this design, a 0.1-µF, 50-V X7R ceramic capacitor is chosen for C_{BOOT}.

8.2.1.3 Application Curves







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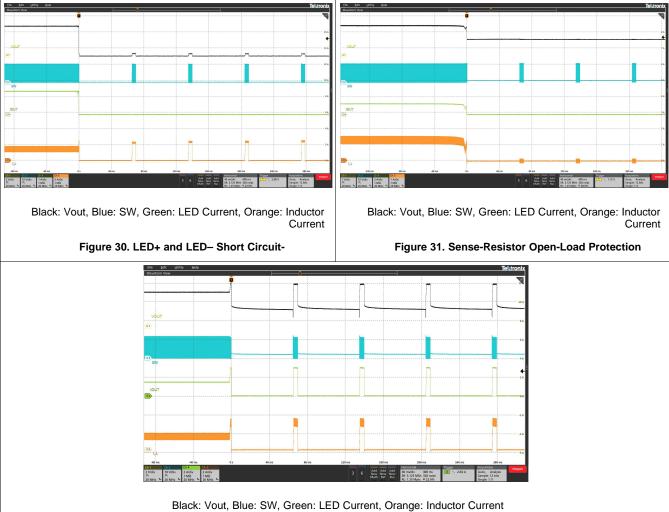


Figure 32. Sense-Resistor Short-to-GND Protection

TEXAS INSTRUMENTS

8.2.2 TPS92200D1 24-V Input, 1-A, 6-Piece WLED Driver with PWM Dimming

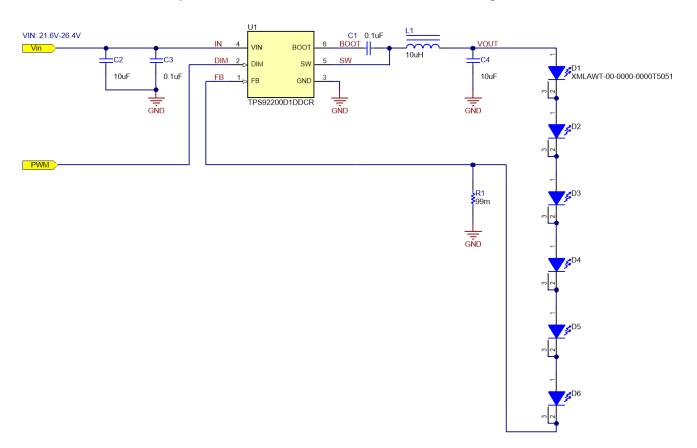


Figure 33. 24-VIN, 1-A, 6-piece WLED, PWM Dimming Reference Design

8.2.2.1 Design Requirements

For this design example, use the parameters in the following table.

Table 4. Design Parameters

PARAMETER	VALUE
Input voltage range	24 V ±10%
LED forward voltage	3 V
Output voltage	18.1 V (3 × 6 + 0.1)
Maximum LED current	1 A
Inductor current ripple	60% of maximum LED current
LED current ripple	20mA or less
Input voltage ripple	200mV or less
Dimming type	PWM dimming with TPS92200D1: 500 Hz, 1% to 100% duty cycle input on the DIM pin



8.2.2.2 Detailed Design Procedure

8.2.2.2.1 Inductor Selection

For this application, input voltage is 24V rail with 10% variation, output is 6 white LEDs in series and the inductor current ripple requirement is less than 60% of maximum LED current. To choose a proper peak-to-peak inductor current ripple, the low-side FET sink current limit should not violated when converter works in no-load condition, this requires the half of peak-to-peak inductor current ripple to be lower than that limit. Another consideration is the increased core loss and copper loss in the inductor with this larger peak-to-peak current ripple which is also acceptable. Once this peak-to-peak inductor current ripple is chosen, use Equation 10 to calculate the recommended value of the output inductor L.

$$L = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times K_{IND} \times I_{LED} \times f_{SW}}$$

where

- K_{IND} is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current.
- I_{LED} is the maximum LED current.

 V_{OUT} is the sum of the voltage across LED load and the voltage across sense resistor. (10)

With the chosen inductor value, the user can calculate the actual inductor-current ripple using Equation 11.

$$I_{L(ripple)} = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times L \times f_{SW}}$$
(11)

In this design, $V_{IN(max)} = 26.4V$, $V_{OUT} = 18.1V$, $I_{LED} = 1A$, choose $K_{IND} = 0.6$, the calculated inductance is $9.49\mu H$. A 10-µH inductor is chosen. With this inductor, the ripple, peak, and rms currents of the inductor are 0.57 A, 1.29 A, and 1.01 A, respectively.

8.2.2.2.2 Input Capacitor Selection

In this design, a 10-uF, 35V X7R ceramic capacitor, part number GRM32ER7YA106KA12L, from muRata is chosen. This yields around 30-mV input-ripple voltage.

8.2.2.2.3 Output Capacitor Selection

The dynamic resistance of this Cree white LED is 0.67 ohm at 1A forward current. In this design, choose a 10µF, 35V X7R ceramic capacitor, part number GRM32ER7YA106KA12L, the calculated ripple current of LED is about 11.5mA.

8.2.2.3.1 Sense Resistor Selection

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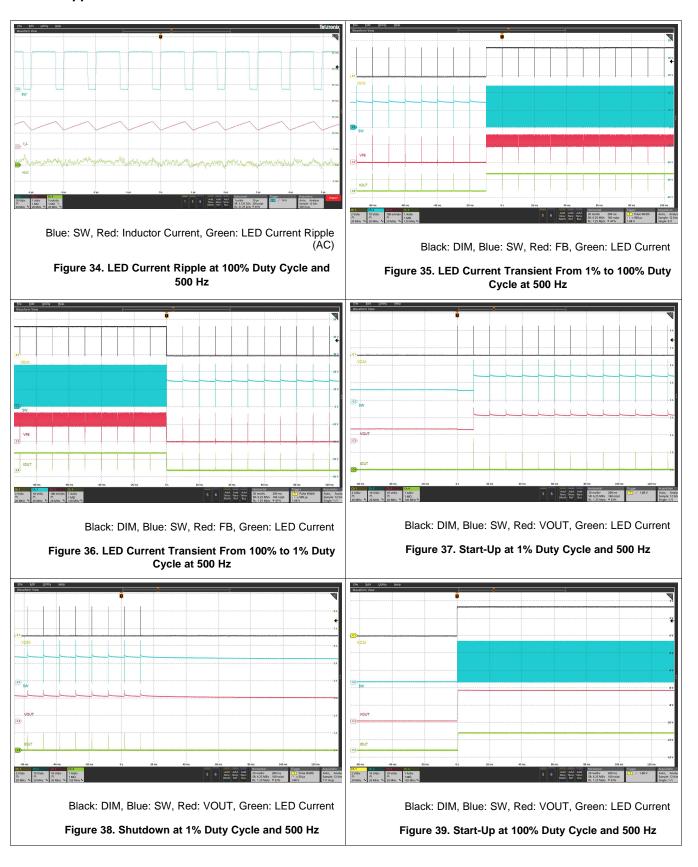
The maximum LED current is 1 A, and the corresponding V_{REF} is 99 mV. Using Equation 1, calculate the needed sense resistance at 99 m Ω . Pay close attention to the power consumption of the sense resistor in this design at 99 mW, and make sure the chosen resistor has enough margin in its power rating.

8.2.2.2.3.1.1 Other External Components Selection

See the Other External Components Selection

INSTRUMENTS

8.2.2.3 Application Curves





www.ti.com Black: DIM, Blue: SW, Red: VOUT, Green: LED Current Black: DIM, Blue: SW, Red: Inductor Current, Green: LED Figure 40. Shutdown at 100% Duty Cycle and 500 Hz Figure 41. LED PWM Dimming at 1% Duty Cycle and 200 Hz Black: DIM, Blue: SW, Red: Inductor Current, Green: LED Black: DIM, Blue: SW, Red: Inductor Current, Green: LED Current Figure 42. LED PWM Dimming at 50% Duty Cycle and 200 Figure 43. LED PWM Dimming at 99% Duty Cycle and 200

Figure 44. LED PWM Dimming at 50% Duty Cycle and 2 kHz

Black: DIM, Blue: SW, Red: Inductor Current, Green: LED

Figure 45. LED PWM Dimming at 99% Duty Cycle and 2 kHz

Black: DIM, Blue: SW, Red: Inductor Current, Green: LED

Current

TEXAS INSTRUMENTS

8.2.3 5-V Input, 1-A, 1-Piece IR LED Driver with TPS92200D2

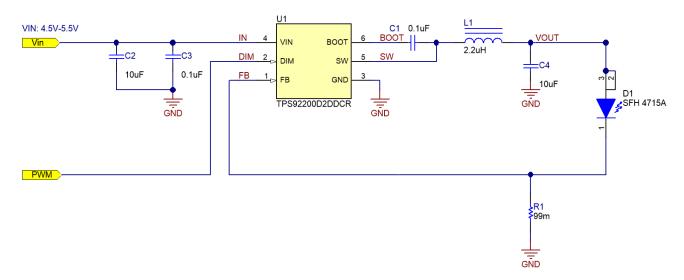


Figure 46. 5-VIN, 1-A, 1-piece IR LED, Analog Dimming Reference Design

8.2.3.1 Design Requirements

For this design example, use the parameters in the below table.

PARAMETER VALUE Input voltage range 5 V ±10% LED forward voltage 1.75 V Output voltage 1.85 V (1.75 + 0.1) Maximum LED current 1 A Inductor current ripple 60% of maximum LED current LED current ripple 20mA or less Input voltage ripple 200mV or less Analog dimming with TPS92200D2: 50 kHz, 1% to 100 % duty cycle Dimming type input on the DIM pin

Table 5. Design Parameters

8.2.3.2 Detailed Design Procedure

8.2.3.2.1 Inductor Selection

For this application, input voltage is 5V rail with 10% variation, output is a single IR LED and the inductor current ripple requirement is less than 60% of maximum LED current.

Use Equation 12 to calculate the minimum value of the output inductor (L_{MIN}).

$$L = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times K_{IND} \times I_{LED} \times f_{SW}}$$

where

K_{IND} is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current.

I_{LED} is the maximum LED current.

V_{OUT} is the sum of the voltage across LED load and the voltage across sense resistor.

With the chosen inductor value, the user can calculate the actual inductor current ripple using Equation 13.



$$I_{L(ripple)} = \frac{V_{OUT} \times (V_{VIN(\max)} - V_{OUT})}{V_{VIN(\max)} \times L \times f_{SW}}$$
(13)

In this design, $V_{IN(max)} = 5.5 \text{ V}$, $V_{OUT} = 1.85 \text{ V}$, $I_{LED} = 1 \text{ A}$, choose $K_{IND} = 0.6$. The calculated inductance is 2.046 μ H. A 2.2 μ H inductor is chosen. With this inductor, the ripple, peak, and RMS currents of the inductor are 0.56 A, 1.28 A, and 1.01 A, respectively.

8.2.3.2.2 Input Capacitor Selection

In this design, a 10-µF, 35V X7R ceramic capacitor, part number GRM32ER7YA106KA12L, from muRata is chosen. This yield around 30-mV input ripple voltage.

8.2.3.2.3 Output Capacitor Selection

The dynamic resistance of this LED is 0.29ohm at 1A forward current. In this deisng, choose a 10µF, 35V X7R ceramic capacitor, part number GRM32ER7YA106KA12L, the calculated ripple current of LED is about 21.9mA.

8.2.3.2.3.1 Sense Resistor Selection

The maximum LED current is 1 A, and the corresponding V_{REF} is 99 mV. Using Equation 1, calculate the needed sense resistance at 99 m Ω . Pay close attention to the power consumption of the sense resistor in this design at 99 mW, and make sure the chosen resistor has enough margin in its power rating.

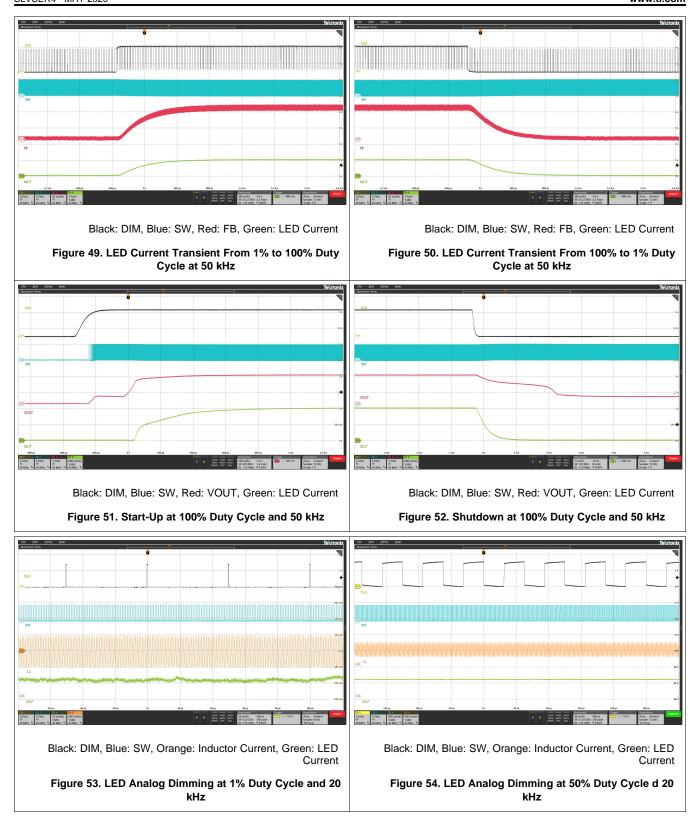
8.2.3.2.3.1.1 Other External Components Selection

See the Other External Components Selection section.

8.2.3.3 Application Curves







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Black: DIM, Blue: SW, Orange: Inductor Current, Green: LED Black: DIM, Blue: SW, Orange: Inductor Current, Green: LED Current Current Figure 55. LED Analog Dimming at 99% Duty Cycle and 20 Figure 56. LED Analog Dimming at 1% Duty Cycle and 200 kHz kHz Black: DIM, Blue: SW, Orange: Inductor Current, Green: LED Black: DIM, Blue: SW, Orange: Inductor Current, Green: LED Current Current Figure 57. LED Analog Dimming at 50% Duty Cycle and Figure 58. LED Analog Dimming at 99% Duty Cycle and

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200 kHz

200 kHz



9 Power Supply Recommendations

The devices are designed to operate from an input voltage supply range between 4 V and 30 V. This input supply must be well regulated. The device requires an input capacitor to reduce the surge current drawn from the input supply and the switching noise from the device. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. For most applications, a 10- μ F capacitor is enough.

10 Layout

The TPS92200 device requires a proper layout for optimal performance. The following section gives some guidelines to ensure a proper layout.

10.1 Layout Guidelines

An example of a proper layout for the TPS92200 device is shown in Figure 59.

- Creating a large GND plane for good electrical and thermal performance is important.
- The IN and GND traces should be as wide as possible to reduce trace impedance. Wide traces have the additional advantage of providing excellent heat dissipation.
- Thermal vias can be used to connect the top-side GND plane to additional printed-circuit board (PCB) layers for heat dissipation and grounding.
- The input capacitors must be located as close as possible to the IN pin and the GND pin.
- The SW trace must be kept as short as possible to reduce radiated noise and EMI.
- Do not allow switching current to flow under the device.
- The FB trace should be kept as short as possible and placed away from the high-voltage switching trace and the ground shield.
- In higher-current applications, routing the load current of the current-sense resistor to the junction of the input capacitor and GND node may be necessary.

10.2 Layout Example

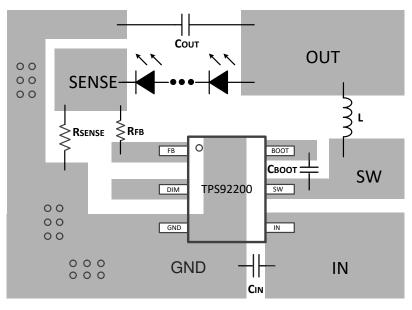


Figure 59. Layout Example



11 Device and Documentation Support

11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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11.3 Trademarks

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Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the mostcurrent data available for the designated devices. This data is subject to change without notice and without revision of this document. For browser-based versions of this data sheet, see the left-hand navigation pane.



PACKAGE OPTION ADDENDUM

19-Jun-2020

PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS92200D1DDCR	ACTIVE	SOT-23-THIN	DDC	6	3000	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM	-40 to 85	1SZK	Samples
TPS92200D2DDCR	ACTIVE	SOT-23-THIN	DDC	6	3000	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM	-40 to 85	1T1K	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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19-Jun-2020

PACKAGE MATERIALS INFORMATION

www.ti.com 18-Jun-2020

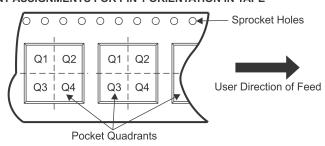
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS92200D1DDCR	SOT- 23-THIN	DDC	6	3000	180.0	9.5	3.17	3.1	1.1	4.0	8.0	Q3
TPS92200D2DDCR	SOT- 23-THIN	DDC	6	3000	180.0	9.5	3.17	3.1	1.1	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

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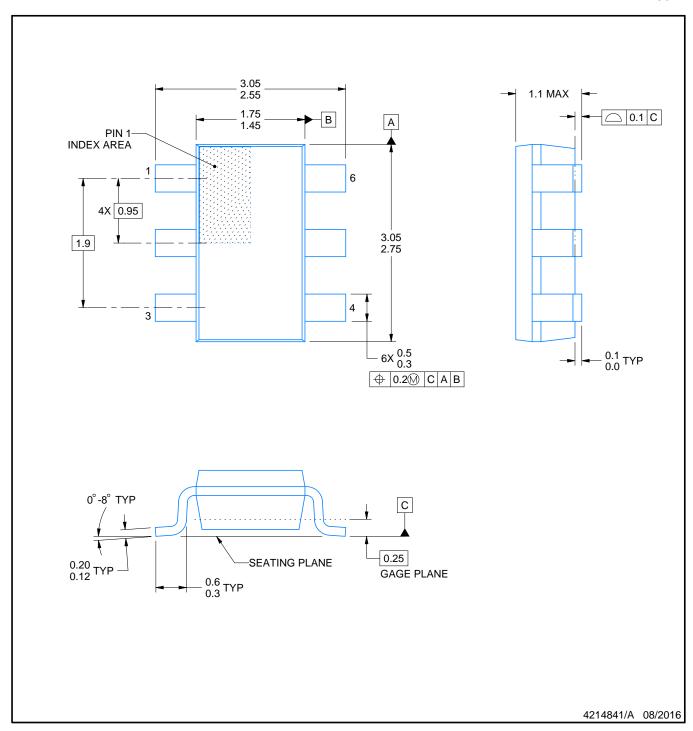


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS92200D1DDCR	SOT-23-THIN	DDC	6	3000	184.0	184.0	19.0
TPS92200D2DDCR	SOT-23-THIN	DDC	6	3000	184.0	184.0	19.0



SOT

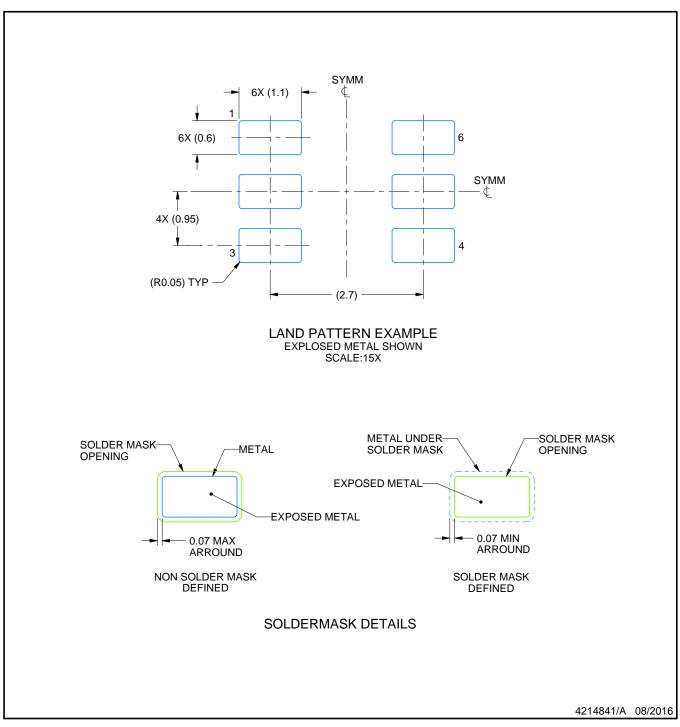


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC MO-193.



SOT

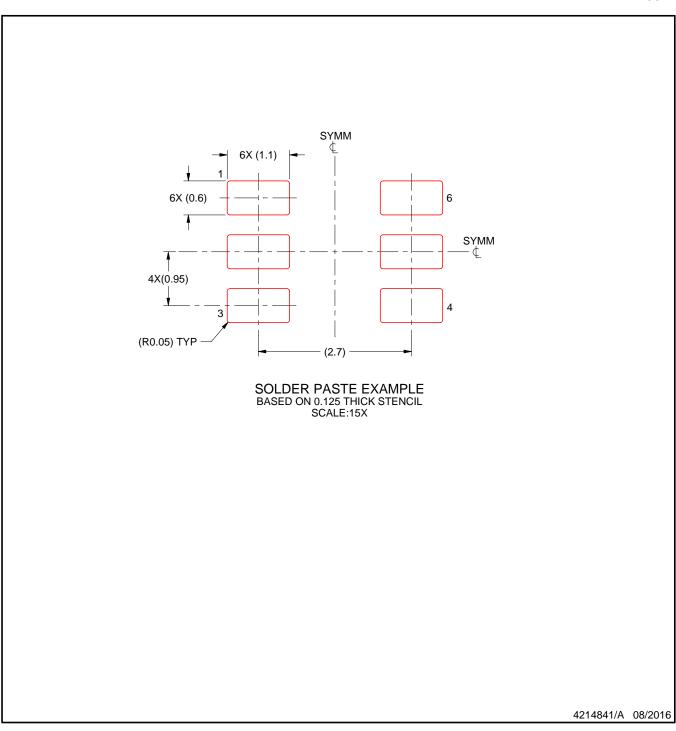


NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOT



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

 7. Board assembly site may have different recommendations for stencil design.



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